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SMT 贴片加工工艺过程中的锡膏印刷缺陷及解决方法

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SMT 贴片加工工艺中，锡膏印刷十分复杂，其对后期产品质量有着非常重要的意义，卓茂光电技术人员主要探讨下锡膏印刷的常见缺陷。

1. 不完全印刷：锡膏的黏度不足，无法有效附着于 PCB 板上或者刮刀磨损；

解决方法：

① 调换锡膏，在选择锡膏时，应考虑到金属颗粒物的大小、粒度是否小于钢网的开孔尺寸；

② 定期检查并更换刮刀；

2. 空焊假焊：锡膏量不足或 PCB 板不合格，易出现假焊、空焊等现象；

解决方法：

① 选择具有一定知名度的 PCB 板品牌生产商，可以降低 PCB 板出现不合格的概率；

② 在锡焊工艺上，确保锡的均匀度以及控制锡量的多少，可以防止锡量少而出现假焊空焊；

③ 锡焊粗糙有毛刺：锡膏黏度低或者钢网开孔粗糙；

④ 在选择锡膏前，注意锡膏的黏度；

为了确保 SMT 工艺的良好，在 SMT 贴片完成后，有实力的企业会对 SMT 进行检测作业，而最常用的检测设备当属 X-RAY 检测设备，其强大的穿透力，可以确保 SMT 无死角的呈现出是否存在缺陷的问题。



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Solder paste printing defects and solutions in SMT chip processing process

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In the SMT chip processing process, solder paste printing is very complicated, and it has very important significance for product quality. This article mainly discusses the common defects of solder paste printing.

1. Incomplete printing: The solder paste has insufficient viscosity and cannot be effectively attached to the PCB or the blade is worn;

Solutions:

① Replace the solder paste. When selecting the solder paste, the size of the solid metal particulates should be considered, and the particle size should be smaller than the opening size of the steel mesh;

② Regularly check and replace the scraper;

2. Solder skip, Non-wetting/false soldering: insufficient solder paste or unqualified PCB, easy to appear Solder skip, Non-wetting/false soldering;

Solutions:

① Choosing a well-known manufacturer of PCB board brands can reduce the probability of PCB board failure;



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②In the soldering process, ensuring the uniformity of tin and controlling the amount of tin can prevent Solder skip, Non-wetting/false soldering;

③Rough and burr of soldering: low viscosity of solder paste or rough opening of steel mesh;

④Pay attention to the viscosity of the solder paste before selecting the solder paste;

In order to ensure the SMT process is good, after the SMT patch is completed, The strong enterprise will test the SMT, and the most commonly used testing equipment is the NDT X-RAY inspection equipment, which has strong penetrating power to ensure SMT 360° shows the problem of whether there is a defect.